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Z86108

CMOS 8-BIT LOW-COST 2K-ROM MICROCONTROLLERS

FEATURES

Part Number	ROM (KB)	RAM* (Bytes)	Speed (MHz)	Auto Latch	Permanent WDT
Z86108	2	125	4	Optional	Optional

Note: * General-Purpose

- 18-Pin DIP and SOIC Packages

- 3.0V to 5.5V Operating Range

- Available Temperature Ranges
  – E = –40°C to +105°C
  – S = 0°C to +70°C

- 14 Input / Output Lines

- Six Vectored, Prioritized Interrupts from Six Different Sources

- Two On-Board Comparators

- Two Programmable 8-Bit Counter/Timers, Each with 6-Bit Programmable Prescaler

- Clock-Free WDT Reset

- Power-On Reset (POR) Timer

- ROM Mask Options:
  – System Clock Divisor
  – ROM Protect
  – Auto Latch
  – Permanent Watch-Dog Timer (WDT)
  – RC Oscillator
  – 32 kHz Operation

- On-Chip Oscillator that Accepts RC, Crystal, Ceramic Resonator, LC, or External Clock Drive

- Low-Power Consumption (50 mw)

- Fast Instruction Pointer (1.5 µs @ 4 MHz)

- Fourteen Digital Inputs at CMOS Levels; Schmitt-Triggered

- Software Enabled Watch-Dog Timer

- Programmable Interrupt Polarity

- Two Standby Modes: STOP and HALT

- Low-Voltage Protection

GENERAL DESCRIPTION

ZiLOG's Z86108 is a member of the Z8® MCU family, offering easy software/hardware system expansion.

For applications demanding powerful I/O capabilities, the Z86108's dedicated input and output lines are grouped into three ports. Each port is configurable under software control to provide timing, status signals, or parallel I/O.

Two on-chip counter/timers, with a large number of user selectable modes, off-load the system of administering real-time tasks such as counting/timing and I/O data communi-

cations. Additionally, two on-board comparators process analog signals with a common reference voltage (Figure 1).

Note: All Signals with an overline, "‾", are active Low. For example, B/$\overline{W}$, in which WORD is active Low), and $\overline{B}$/W, in which BYTE is active Low.

GENERAL DESCRIPTION (Continued)

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}
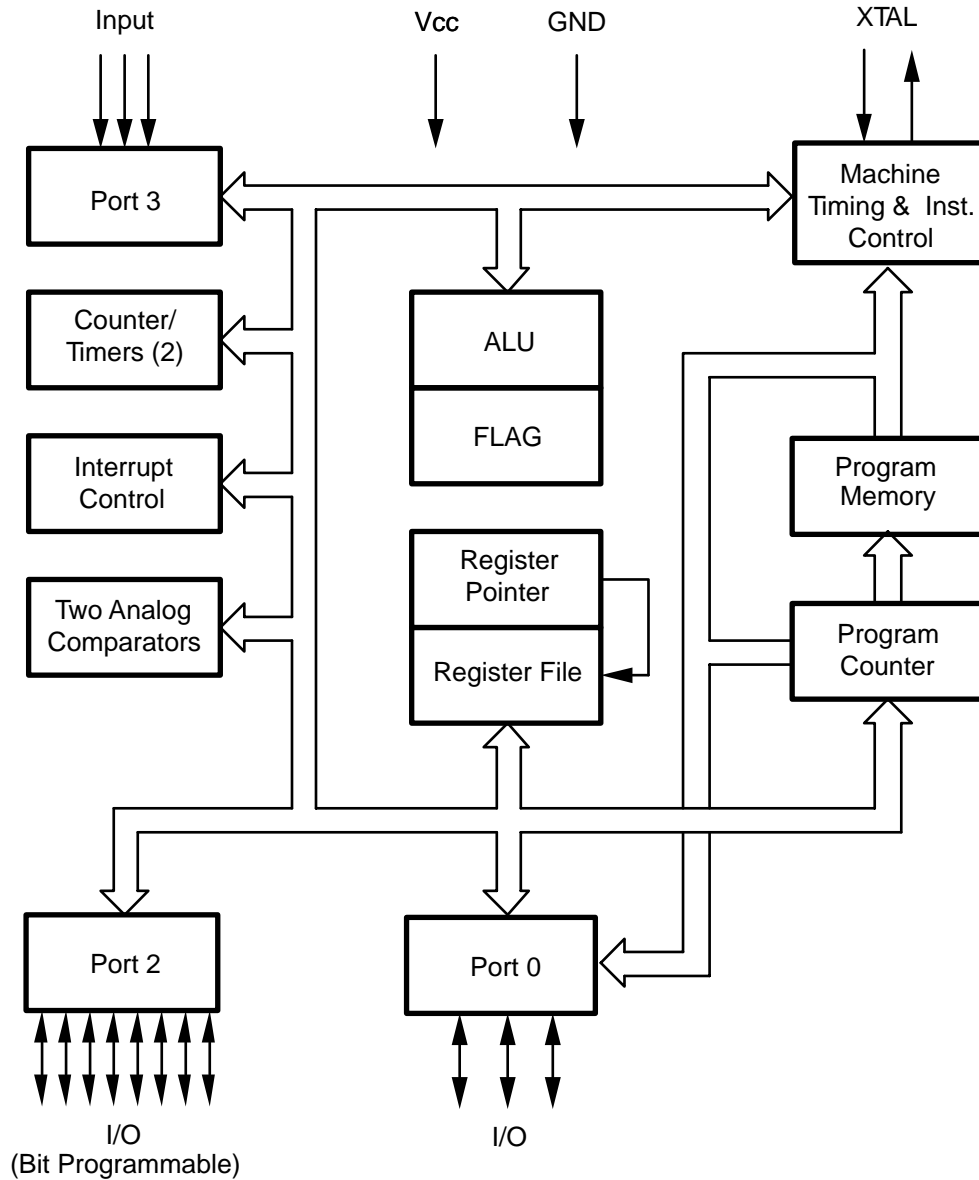
Figure 1. Z86108 Functional Block Diagram

PIN DESCRIPTION

```
        P24 ⌷   1        18  ⌷ P23
        P25 ⌷   2        17  ⌷ P22
        P26 ⌷   3        16  ⌷ P21
        P27 ⌷   4        15  ⌷ P20
        Vcc ⌷   5  DIP   14  ⌷ GND
      XTAL2 ⌷   6        13  ⌷ P02
      XTAL1 ⌷   7        12  ⌷ P01
        P31 ⌷   8        11  ⌷ P00
        P32 ⌷   9        10  ⌷ P33
```

Figure 2. 18-Pin DIP

```
        P24 ⌷   1        18  ⌷ P23
        P25 ⌷   2        17  ⌷ P22
        P26 ⌷   3        16  ⌷ P21
        P27 ⌷   4        15  ⌷ P20
        Vcc ⌷   5  SOIC  14  ⌷ GND
      XTAL2 ⌷   6        13  ⌷ P02
      XTAL1 ⌷   7        12  ⌷ P01
        P31 ⌷   8        11  ⌷ P00
        P32 ⌷   9        10  ⌷ P33
```
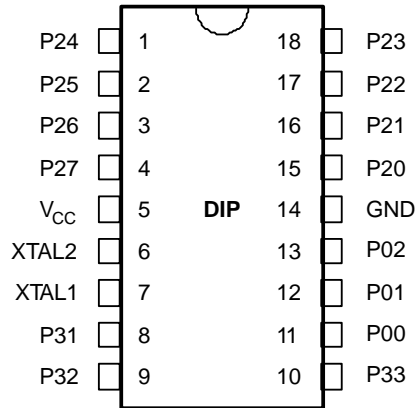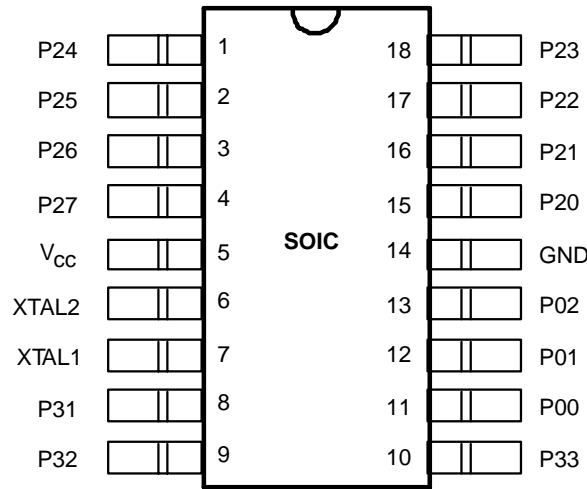
Figure 3. 18-Pin SOIC

Table 1: 18-Pin DIP and SOIC Pin Identification

Pin #	Symbol	Function	Direction
1-4	P24-P27	Port 2, Pins 4, 5, 6, 7	In/Output
5	V_{CC}	Power Supply	
6	XTAL2	Crystal Oscillator Clock	Output
7	XTAL1	Crystal Oscillator Clock	Input
8	P31	Port 3, Pin 1, AN1	Input
9	P32	Port 3, Pin 2, AN2	Input
10	P33	Port 3, Pin 3, REF	Input
11-13	P00-P02	Port 0, Pins 0, 1, 2	In/Output
14	GND	Ground	
15-18	P20-P23	Port 2, Pins 0, 1, 2, 3	In/Output

PIN DESCRIPTION (Continued)

XTAL1, XTAL2. *Crystal In, Crystal Out* (time-based input and output, respectively). These pins connect a RC, parallel-resonant crystal, LC, or an external single-phase clock to the on-chip clock oscillator and buffer.

Auto Latch. The Auto Latch puts valid CMOS levels on all CMOS inputs (except P33, P32, P31) that are not externally driven. After Power-On Reset, the level, whether a 0 or 1, cannot be determined. A valid CMOS level, rather than a floating node, reduces excessive supply current flow in the

input buffer. To change the Auto Latch state, the auto latches must be over driven with current greater than I_{ALH} (High to low) or I_{ALL} (low to High).

Port 0 (P02–P00). Port 0 is a 3-bit I/O, bidirectional, Schmitt-triggered CMOS-compatible I/O port. These three I/O lines can be configured under software control to be all inputs or all outputs (Figure 4).
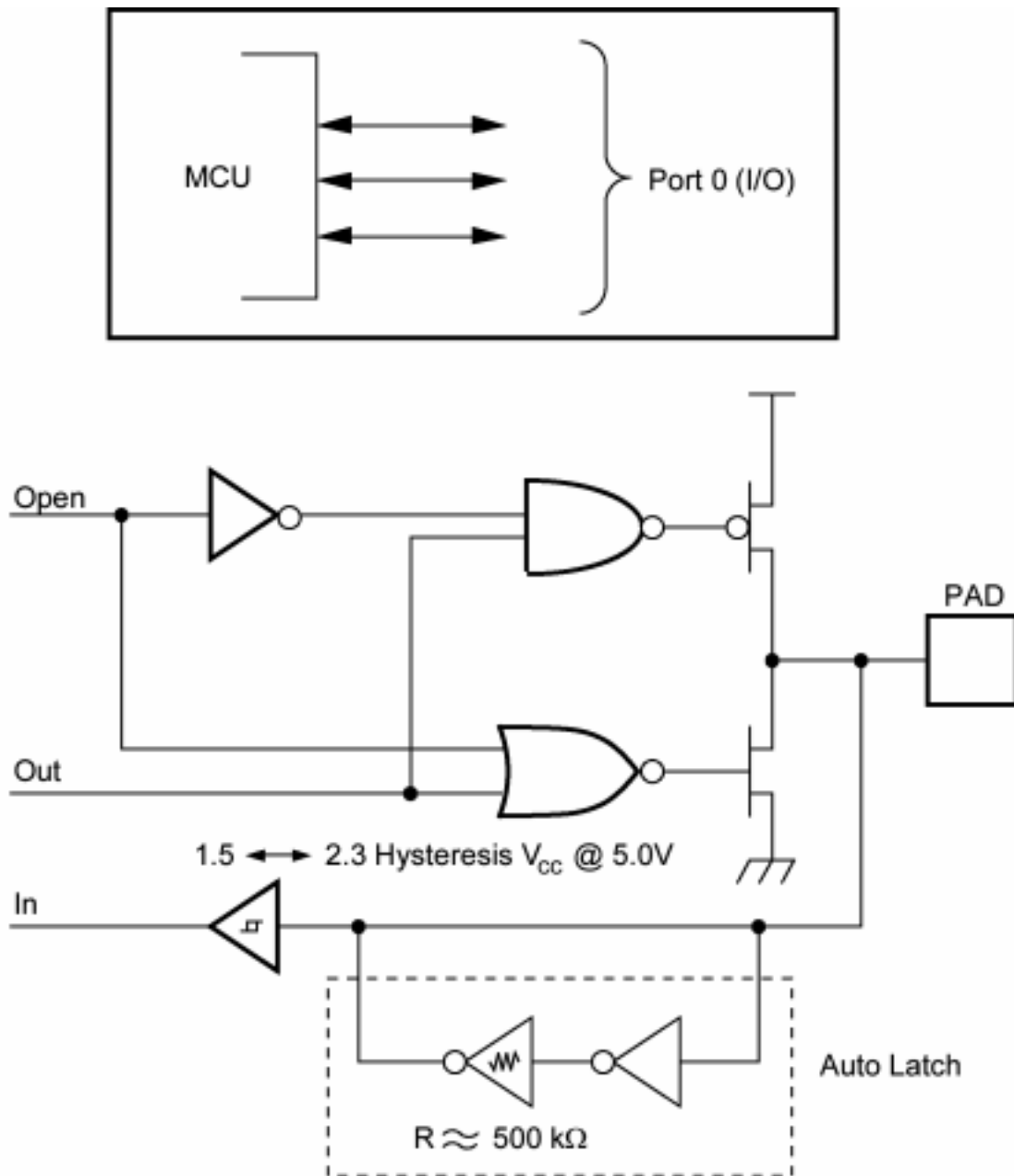

Figure 4. Port 0 Configuration

Port 2 (P27–P20). Port 2 is an 8-bit I/O, bit-programmable, bidirectional, Schmitt-triggered CMOS-compatible I/O port. These eight I/O lines can be configured under software control to be an input or output, independently. Bits programmed as outputs may be globally programmed as either push-pull or open-drain (Figure 5).
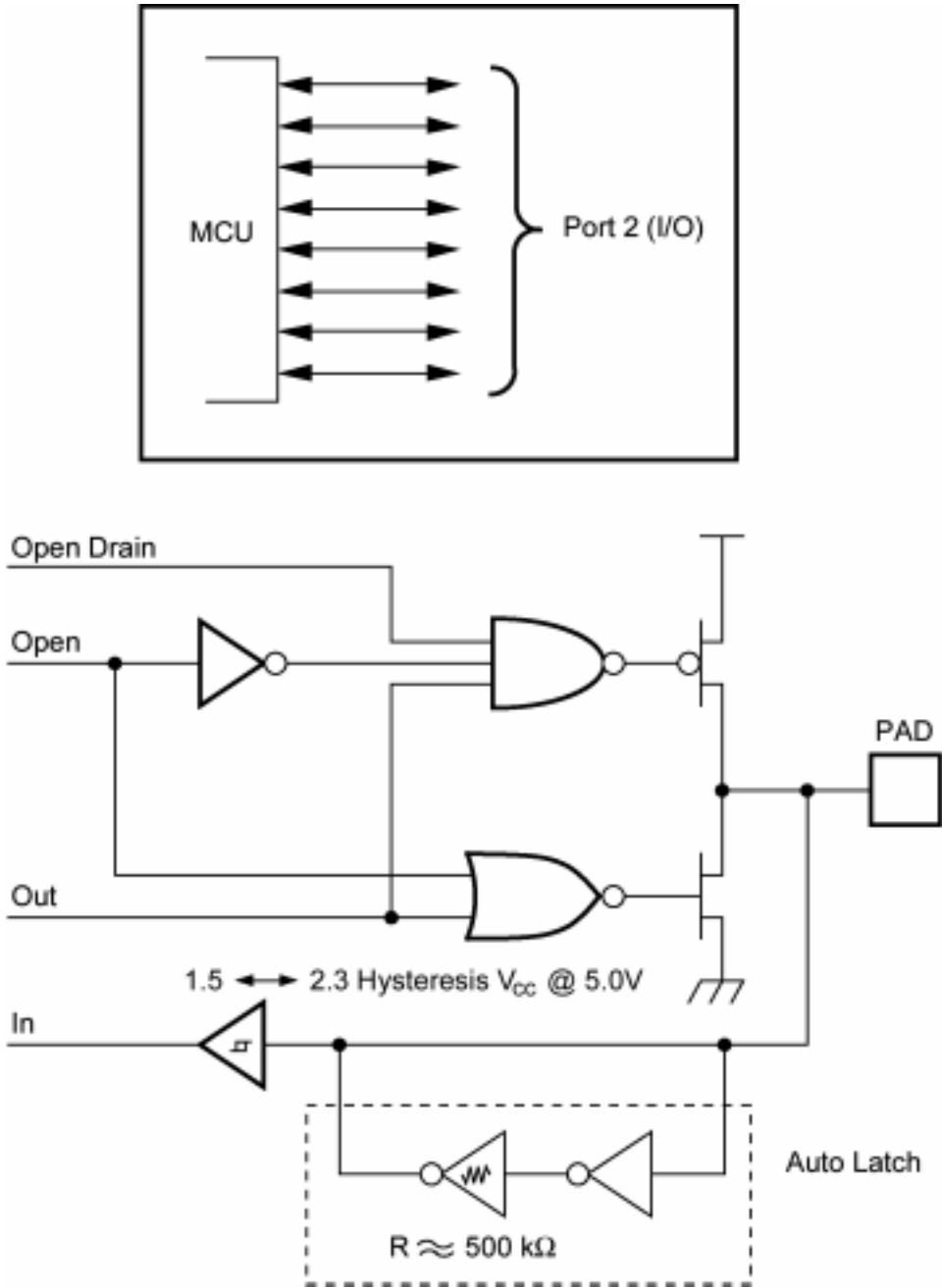

Figure 5. Port 2 Configuration

Port 3 (P33-P31). Port 3 is a 3-bit, Schmitt-triggered CMOS-compatible port with three fixed input (P33–P31) lines. These three input lines can be configured under software control as digital inputs or analog inputs. These three input lines can also be used as the interrupt sources IRQ0–IRQ3 and as the timer input signal (T_{IN}) (Figure 6).
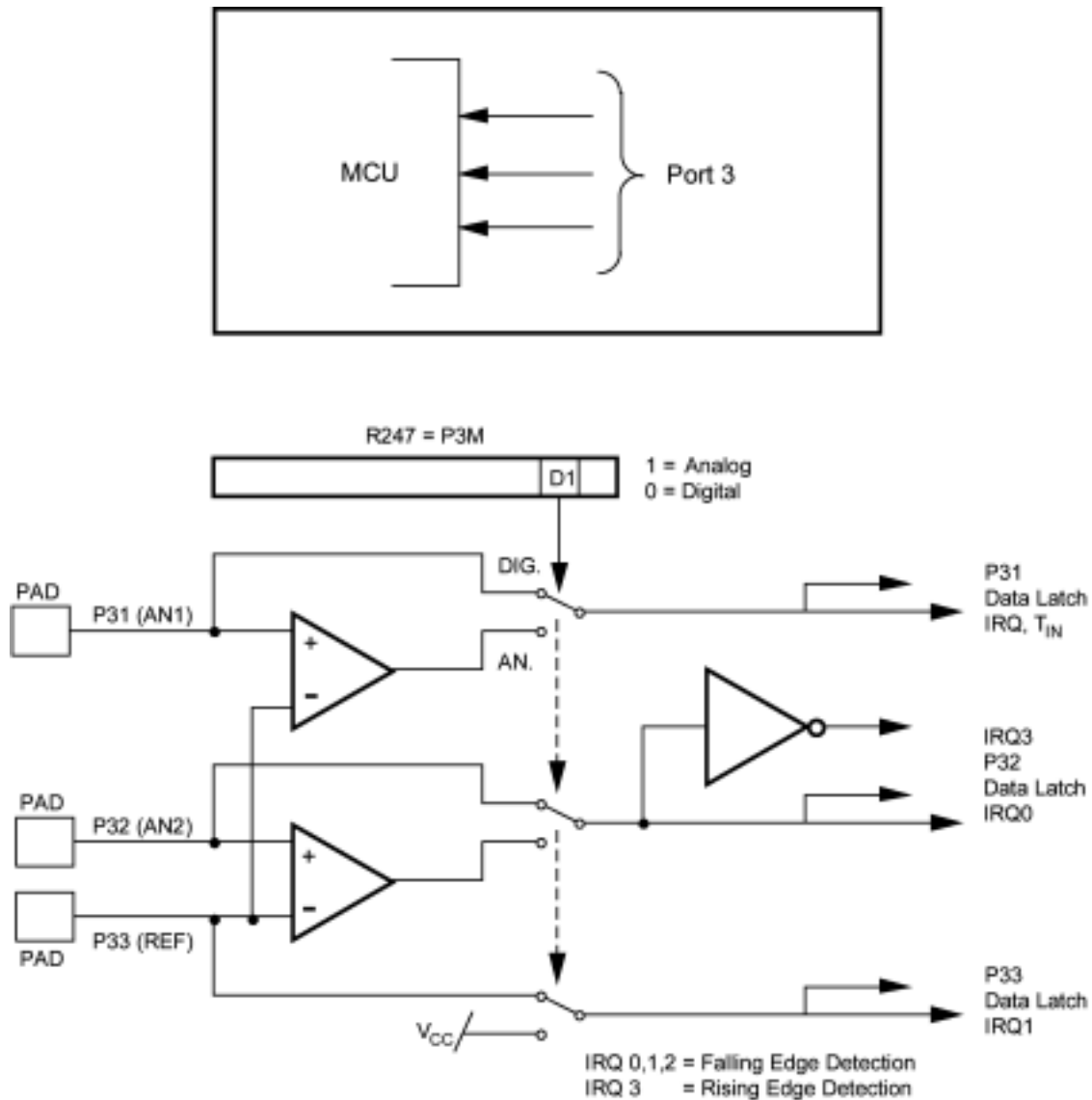
PIN DESCRIPTION (Continued)

Figure 6. Port 3 Configuration

Comparator Inputs. Two analog comparators are added to Port 3 inputs for interface flexibility. Typical applications for these on-board comparators are: Zero crossing detection, A/D conversion, voltage scaling, and threshold detection.

The dual comparator (common inverting terminal) features a single power supply that discontinues power in STOP Mode. The common voltage range is 0–4V when the V_{CC} is 5.0V. Before the comparator outputs are valid, two NOP delays are required after enabling the analog comparators.

Interrupts are generated on either edge of Comparator 2's output, or on the falling edge of Comparator 1's output. The comparator output may be used for interrupt generation, Port 3 data inputs, or T_{IN} through P31. Alternately, the comparators may be disabled, freeing the reference input (P33) for use as IRQ1 and/or P33 input.

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units	Notes
Ambient Temperature under Bias	−40	+105	C	
Storage Temperature	−65	+150	C	
Voltage on any Pin with Respect to V_{SS}	−0.7	+12	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	−0.3	+7	V	
Voltage on Pin 7 with Respect to V_{SS}	−0.7	V_{DD}+1	V	2
Total Power Dissipation		462	mW	
Maximum Current out of V_{SS}		84	mA	
Maximum Current into V_{DD}		84	mA	
Maximum Current into an Input Pin	−600	+600	µA	3
Maximum Current into an Open-Drain Pin	−600	+600	µA	4
Maximum Output Current Sinked by Any I/O Pin		12	mA	
Maximum Output Current Sourced by Any I/O Pin		12	mA	
Total Maximum Output Current Sinked by Port 2		70	mA	
Total Maximum Output Current Sourced by Port 2		70	mA	

Notes:
1. This applies to all pins except where otherwise noted. Maximum current into pin must be ±600µA.
2. There is no input protection diode from pin to V_{DD}.
3. This excludes Pin 6 and Pin 7.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

Total Power dissipation = V_{DD} x [I_{DD} − (sum of I_{OH})]
+ sum of [(V_{DD} − V_{OH}) x I_{OH}]
+ sum of (V_{OL} x I_{OL}).

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 7).
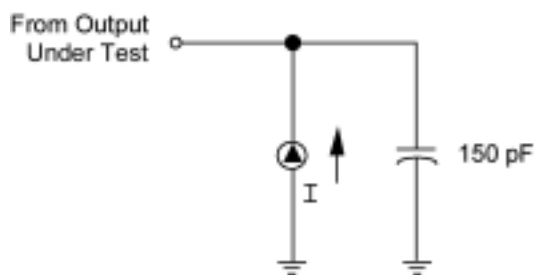

Figure 7. Test Load Diagram

CAPACITANCE

T_A= 25°C, V_{CC} = GND = 0V, f = 1.0 MHz, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	15 pF
Output capacitance	0	20 pF
I/O capacitance	0	25 pF

DC CHARACTERISTICS

Table 1. DC Characteristics[1]

Symbol	Parameter	V_{CC}	T_A= 0°C to +70°C		T_A= −40°C to +105°C		Typical @ 25°C	Units	Conditions	Notes
			Min	Max	Min	Max				
V_{CH}	Clock Input High Voltage	3.0V	$0.8\,V_{CC}$	V_{CC}+0.3	$0.8\,V_{CC}$	V_{CC}+0.3	1.7	V	Driven by External Clock Generator	
		5.5V	$0.8\,V_{CC}$	V_{CC}+0.3	$0.8\,V_{CC}$	V_{CC}+0.3	2.8	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	3.0V	V_{SS}−0.3	$0.2\,V_{CC}$	V_{SS}−0.3	$0.2\,V_{CC}$	0.8	V	Driven by External Clock Generator	
		5.5V	V_{SS}−0.3	$0.2\,V_{CC}$	V_{SS}−0.3	$0.2\,V_{CC}$	1.7	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	3.0V	$0.7\,V_{CC}$	V_{CC}+0.3	$0.7\,V_{CC}$	V_{CC}+0.3	1.8	V		2
		5.5V	$0.7\,V_{CC}$	V_{CC}+0.3	$0.7\,V_{CC}$	V_{CC}+0.3	2.8	V		2
V_{IL}	Input Low Voltage	3.0V	V_{SS}−0.3	$0.2\,V_{CC}$	V_{SS}−0.3	$0.2\,V_{CC}$	0.8	V		2
		5.5V	V_{SS}−0.3	$0.2\,V_{CC}$	V_{SS}−0.3	$0.2\,V_{CC}$	1.5	V		2
V_{OH}	Output High Voltage	3.0V	V_{CC}−0.4		V_{CC}−0.4		3.0	V	I_{OH} = −2.0 mA	
		5.5V	V_{CC}−0.4		V_{CC}−0.4		4.8	V	I_{OH} = −2.0 mA	
V_{OL1}	Output Low Voltage	3.0V		0.8		0.8	0.2	V	I_{OL}= +4.0 mA	
		5.5V		0.4		0.4	0.1	V	I_{OL}= +4.0 mA	
V_{OL2}	Output Low Voltage	3.0V		1.0		1.0	0.8	V	I_{OL} = +12 mA	
		5.5V		0.8		0.8	0.3	V	I_{OL} = +12 mA	
V_{OFFSET}	Comparator Input Offset Voltage	3.0V		25		25	10	mV		
		5.5V		25		25	10	mV		
V_{LV}	V_{CC} Low Voltage Auto Reset		2.0	2.8			2.6	V	Int. CLK Freq @ 4 MHz Max.	
					1.8	3.0	2.6	V	Int. CLK Freq @ 4 MHz Max.	
I_{IL}	Input Leakage (Input Bias Current of Comparator)	3.0V	−1.0	1.0	−1.0	1.0		µA	V_{IN} = 0V, V_{CC}	
		5.5V	−1.0	1.0	−1.0	1.0		µA	V_{IN} = 0V, V_{CC}	
I_{OV}	Output Leakage	3.0V	−1.0	1.0	−1.0	1.0		µA	V_{IN} = 0V, V_{CC}	
		5.5V	−1.0	1.0	−1.0	1.0		µA	V_{IN} = 0V, V_{CC}	
V_{ICR}	Comparator Input Common Mode Voltage Range		0	V_{CC}−1.0	0	V_{CC}−1.5		V		
I_{CC}	Supply Current (SCLK=XTAL/2)	3.0V		3.5		3.5	1.5	mA	All Output and I/O Pins Floating @ 2 MHz	3,5
		5.5V		7.0		7.0	3.8	mA	All Output and I/O Pins Floating @ 2 MHz	3,5
		3.0V		5.8		5.8	2.5	mA	All Output and I/O Pins Floating @ 4 MHz	3,5
		5.5V		9.0		9.0	4.0	mA	All Output and I/O Pins Floating @ 4 MHz	3,5

Table 1. DC Characteristics[1] (Continued)

Symbol	Parameter	V_{CC}	T_A= 0°C to +70°C Min	Max	T_A= −40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC1}	Standby Current (SCLK=XTAL/2)	3.0V		2.5		2.5	0.7	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	3,5
		5.5V		4.0		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	3,5
		3.0V		4.0		4.0	1.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	3,5
		5.5V		5.0		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	3,5
I_{CC}	Supply Current (SCLK=XTAL/1)	3.0V		3.5		3.5	1.5	mA	All Output and I/O Pins Floating @ 1 MHz	4
		5.5V		7.0		7.0	3.8	mA	All Output and I/O Pins Floating @ 1 MHz	4
		3.0V		5.8		5.8	2.5	mA	All Output and I/O Pins Floating @ 2 MHz	4
		5.5V		9.0		9.0	4.0	mA	All Output and I/O Pins Floating @ 2 MHz	4
		3.0V		8.0		8.0	3.0	mA	All Output and I/O Pins Floating @ 4 MHz	4
		5.5V		11.0		11.0	4.4	mA	All Output and I/O Pins Floating @ 4 MHz	4
I_{CC1}	Standby Current (SCLK=XTAL/1)	3.0V		3.0		3.0	0.7	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	4
		5.5V		4.0		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	4
		3.0V		4.0		4.0	0.9	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	4
		5.5V		5.0		5.0	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4MHz	4
I_{CC2}	Standby Current	3.0V		10		20	1.0	µA	STOP Mode V_{IN} = 0V,V_{CC} WDT is not Running	7
		5.5V		10		20	1.0	µA	STOP Mode V_{IN} = 0V,V_{CC} WDT is not Running	5
I_{ALL}	Auto Latch Low Current	3.0V		12		8.0	3.0	µA	0V < V_{IN} < V_{CC}	
		5.5V		30		32	16	µA	0V < V_{IN} < V_{CC}	

P R E L I M I N A R Y

DC CHARACTERISTICS (Continued)

Table 1. DC Characteristics[1] (Continued)

Symbol	Parameter	V_{CC}	T_A= 0°C to +70°C		T_A= −40°C to +105°C		Typical @ 25°C	Units	Conditions	Notes
			Min	Max	Min	Max				
I_{ALH}	Auto Latch High Current	3.0V		−8		−5.0	−1.5	μA	$0V < V_{IN} < V_{CC}$	
		5.5V		−16		−20	−8.0	μA	$0V < V_{IN} < V_{CC}$	

Notes:

1. V_{SS} = 0V = GND;
   The device operates down to V_{LV}. The minimum operational V_{CC} is determined on the value of the voltage V_{LV} at the ambient temperature. The V_{LV} increases as the temperature decreases.
   V_{CC} = 3.0V to 5.5V, typical values measured at V_{CC} = 3.3V and V_{CC} = 5.0V.
2. Port 0, 2, and 3 only.
3. SCLK=XTAL/2.
4. SCLK=XTAL/1.
5. Inputs at power rail and outputs are unloaded.
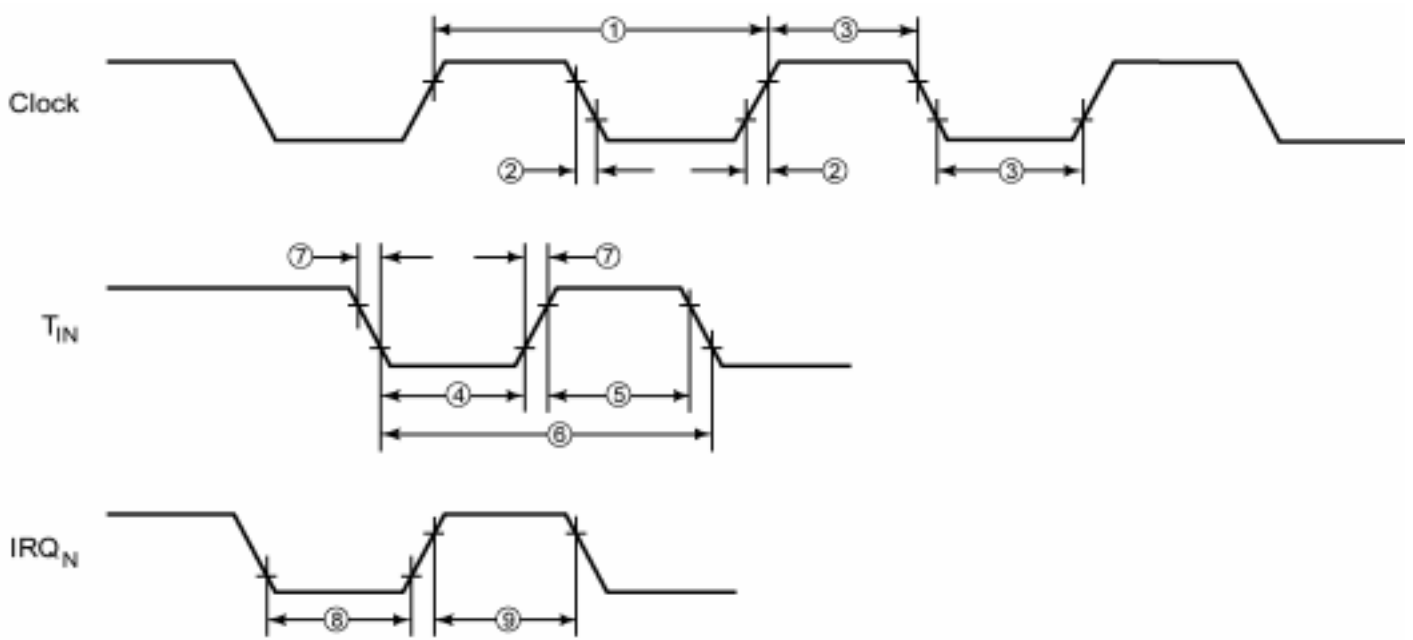
AC ELECTRICAL CHARACTERISTICS

Figure 8. AC Electrical Timing Diagram

AC ELECTRICAL CHARACTERISTICS (Continued)

No	Symbol	Parameter	V_{CC}	T_A= 0°C to +70°C				T_A= −40°C to +105°C				Units	Notes
				2 MHz		4 MHz		2 MHz		4 MHz			
				Min	Max	Min	Max	Min	Max	Min	Max		
1	TpC	Input Clock Period	3.0V	500	DC	250	DC	500	DC	250	DC	ns	1
			5.5V	500	DC	250	DC	500	DC	250	DC	ns	1
2	TrC,TfC	Clock Input Rise and Fall Times	3.0V		25		15		25		15	ns	1
			5.5V		25		15		25		15	ns	1
3	TwC	Input Clock Width	3.0V	240		120		240		120		ns	1
			5.5V	240		120		240		120		ns	1
4	TwTinL	Timer Input Low Width	3.0V	100		100		100		100		ns	1
			5.5V	70		70		70		70		ns	1
5	TwTinH	Timer Input High Width	3.0V	5TpC		5TpC		5TpC		5TpC			1
			5.5V	5TpC		5TpC		5TpC		5TpC			1
6	TpTin	Timer Input Period	3.0V	8TpC		8TpC		8TpC		8TpC			1
			5.5V	8TpC		8TpC		8TpC		8TpC			1
7	TrTin, TfTin	Timer Input Rise and Fall Time	3.0V		100		100		100		100	ns	1
			5.5V		100		100		100		100	ns	1
8	TwIL	Int. Request Input Low Time	3.0V	100		100		100		100		ns	1,2
			5.5V	70		70		70		70		ns	1,2
9	TwIH	Int. Request Input High Time	3.0V	5TpC		5TpC		5TpC		5TpC			1
			5.5V	5TpC		5TpC		5TpC		5TpC			1,2
10	Twdt	Watch-Dog Timer Delay Time Before Timeout	3.0V	25		25		25		25		ms	
			5.5V	10		10		8		8		ms	
11	Tpor	Power-On Reset Time	3.0V	6	30	6	30	4	30	4	30	ms	
			5.5V	3	15	3	15	2	15	2	15	ms	

Notes:
1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request through Port 3 (P33–P31)

SYSTEM CLOCK (SCLK) DIVISOR OPTION

The Z8® MCU can be programmed to operate in SCLK=XTAL/1 mode by means of a mask ROM bit option. Use of this feature results in:

- Internal system clock (SCLK/TCLK) operation limited to a maximum of 4 MHz—250 ns cycle time.

- Oscillator divide-by-two circuitry eliminated.

The SCLK=XTAL/1 mode is mask-programmable to be selected by the customer at the time the ROM code is submitted; otherwise SCLK=XTAL/2.

Application Precautions:

1. Emulator does not support the 32 kHz operation.

2. The WDT only runs in Stop Mode if the permanent WDT option is selected.

3. The registers %FE (GPR) and %FF (SPL) are reset to 00Hex after Stop Mode recovery or any reset.

4. Must wait two NOPS before analog comparator outputs are valid after enabling analog mode.

5. Must disable interrupts, enable the analog comparator, and then clear IRQ3 to IRQ0 when switching from digital to analog mode.

FUNCTIONAL DESCRIPTION

RESET. Upon power-up, the Power-On Reset circuit waits for T_{POR} ms (plus 18 clock cycles), and then starts program execution at address %000C (Hex) (Figure 9). The device control registers' reset value is shown in Table 2.
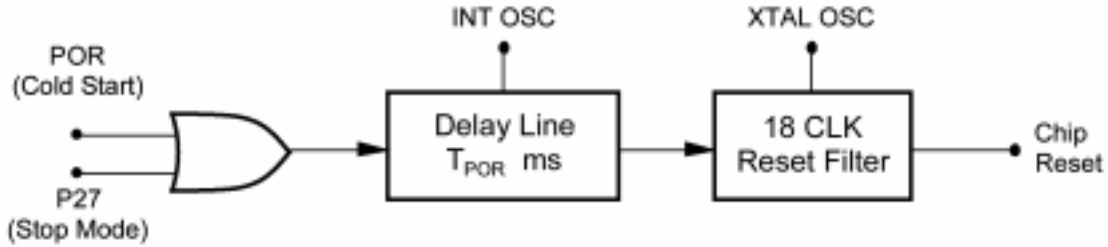
Figure 9. Internal Reset Configuration

Table 2. Control Registers

		Reset Condition								
Addr.	Reg.	D7	D6	D5	D4	D3	D2	D1	D0	Comments
03H (3)*	Port 3	U	U	U	U	U	U	U	U	
02H (2)*	Port 2	U	U	U	U	U	U	U	U	
00H (0)*	Port 0	U	U	U	U	U	U	U	U	
FFH(255)	SPL	0	0	0	0	0	0	0	0	
FEH (254)	GPR	0	0	0	0	0	0	0	0	
FDH (253)	RP	0	0	0	0	0	0	0	0	
FCH (252)	FLAGS	U	U	U	U	U	U	U	U	
FBH (251)	IMR	0	U	U	U	U	U	U	U	
FAH (250)	IRQ	U	U	0	0	0	0	0	0	IRQ3 is used for positive edge detection
F9H (249)	IPR	U	U	U	U	U	U	U	U	
F8H (248)*	P01M	U	U	U	0	U	U	0	1	
F7H (247)*	P3M	U	U	U	U	U	U	0	0	
F6H (246)*	P2M	1	1	1	1	1	1	1	1	Inputs after reset
F5H (245)	PRE0	U	U	U	U	U	U	U	0	
F4H (244)	T0	U	U	U	U	U	U	U	U	
F3H (243)	PRE1	U	U	U	U	U	U	0	0	
F2H (242)	T1	U	U	U	U	U	U	U	U	
F1H (241)	TMR	0	0	0	0	0	0	0	0	

Note: *Registers are not reset after a Stop-Mode Recovery using the P27 pin. A subsequent reset will cause these control registers to be reconfigured as shown. The user must avoid bus contention on the port pins, which may affect device reliability.

Program Memory. The Z8 can address up to 2KB of internal program memory (Figure 10). The first 12 bytes of program memory are reserved for the interrupt vectors. These locations contain six 16-bit vectors that correspond to the six available interrupts. Bytes 0–2047 are on-chip mask-programmed ROM.

Register File. The Register File consists of three I/O port registers, 125 general-purpose registers, and 14 control and status registers (R0, R2–R3, R4–R127, and R241–R255, respectively; see Figure 11).

Note: R254 is available for general purpose use.

Location		
2047	On-Chip ROM	7FFH
Location of First Byte of Instruction Executed After RESET 12		0CH
11	IRQ5	0BH
10	IRQ5	0AH
9	IRQ4	09H
8	IRQ4	08H
7	IRQ3	07H
Interrupt Vector (Lower Byte) 6	IRQ3	06H
5	IRQ2	05H
4	IRQ2	04H
Interrupt Vector (Upper Byte) 3	IRQ1	03H
2	IRQ1	02H
1	IRQ0	01H
0	IRQ0	00H
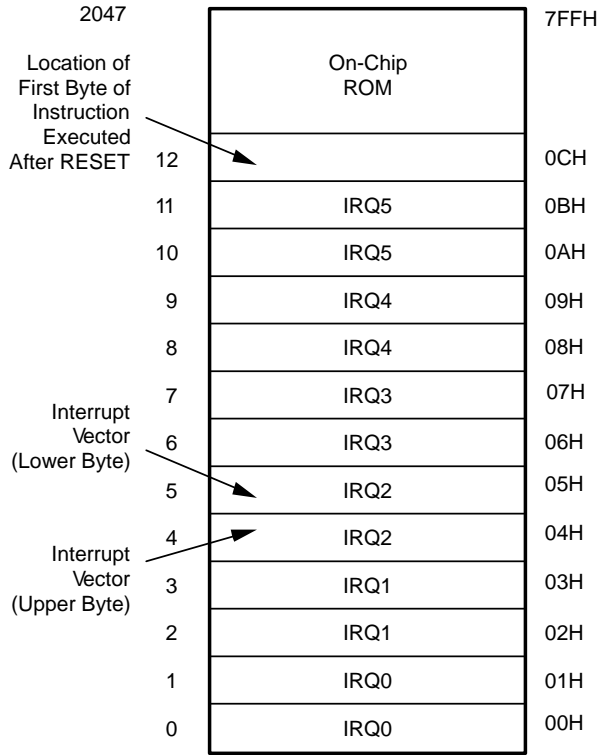
Figure 10. Program Memory Map

Location		Identifiers
255	Stack Pointer (Bits 7-0)	SPL
254	General-Purpose Register	
253	Register Pointer	RP
252	Program Control Flags	Flags
251	Interrupt Mask Register	IMR
250	Interrupt Request Register	IRQ
249	Interrupt Priority Register	IPR
248	Ports 0-1 Mode	P01M
247	Port 3 Mode	P3M
246	Port 2 Mode	P2M
245	To Prescaler	PRE0
244	Timer/Counter0	T0
243	T1 Prescaler	PRE1
242	Timer/Counter1	T1
241	Timer Mode	TMR
240 / 128	Not Implemented	
127 / 4	General Purpose Registers	
3	Port 3	P3
2	Port 2	P2
1	Reserved	P1
0	Port 0	P0

Figure 11. Register File

FUNCTIONAL DESCRIPTION (Continued)

The Z8 instructions can access registers directly or indirectly through an 8-bit address field. This field allows short 4-bit register addressing using the Register Pointer. In the 4-bit mode, the register file is divided into eight working register groups, each occupying 16 continuous locations. The Register Pointer (Figure 12) addresses the starting location of the active working-register group. Upon power-up, the general purpose registers are undefined.

Stack Pointer. The Z8 has an 8-bit Stack Pointer (R255) used for the internal stack that resides within the 125 general-purpose registers.

General-Purpose Register (GPR). The general-purpose register upon device power-up is undefined. The general-purpose register upon a Stop-Mode Recovery and reset stays in its last state. The register may not keep its last state from a V_{LV} reset if the V_{CC} drops below 2.6V.

Note: Register R254 has been designated as a general-purpose register and is set to 00H after any reset.
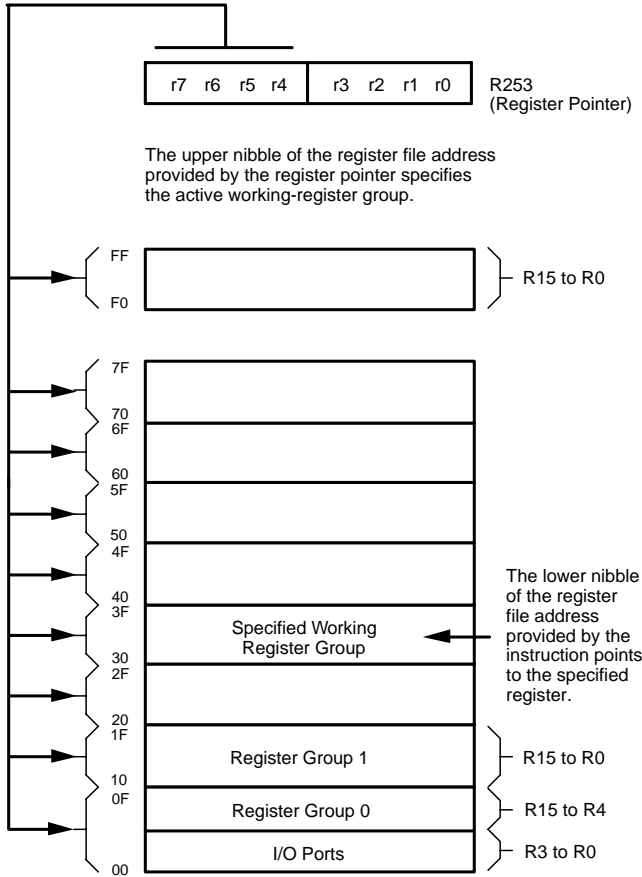
Figure 12. Register Pointer

P R E L I M I N A R Y

Counter/Timer. There are two 8-bit programmable counter/timers (T0 and T1). Each timer is driven by its own 6-bit programmable prescaler. The T1 prescaler can be driven by internal or external clock source; however, the T0 can be driven by the internal clock source only (Figure 13).

The 6-bit prescalers can divide the input frequency of the clock source by any integer number from 1 to 64. Each prescaler drives its counter, which decrements the value (1 to 256) that has been loaded into the counter. When both the counter and prescaler reach the end of count, a timer interrupt request, IRQ4 (T0) or IRQ5 (T1), is generated.

The counter can be programmed to start, stop, restart to continue, or restart from the initial value. The counters can also be programmed to stop upon reaching zero (single pass mode), or automatically reload the initial value and continue counting (modulo-n continuous mode).

The counters, not the prescalers, are read at any time without disturbing their value or count mode. The clock source for T1 is user-definable and can be either the internal microprocessor clock divided by four, or an external signal input through Port 3. The Timer Mode register configures the external timer input (P31) as an external clock, a trigger input that is retriggerable or non-retriggerable, or as a gate input for the internal clock.
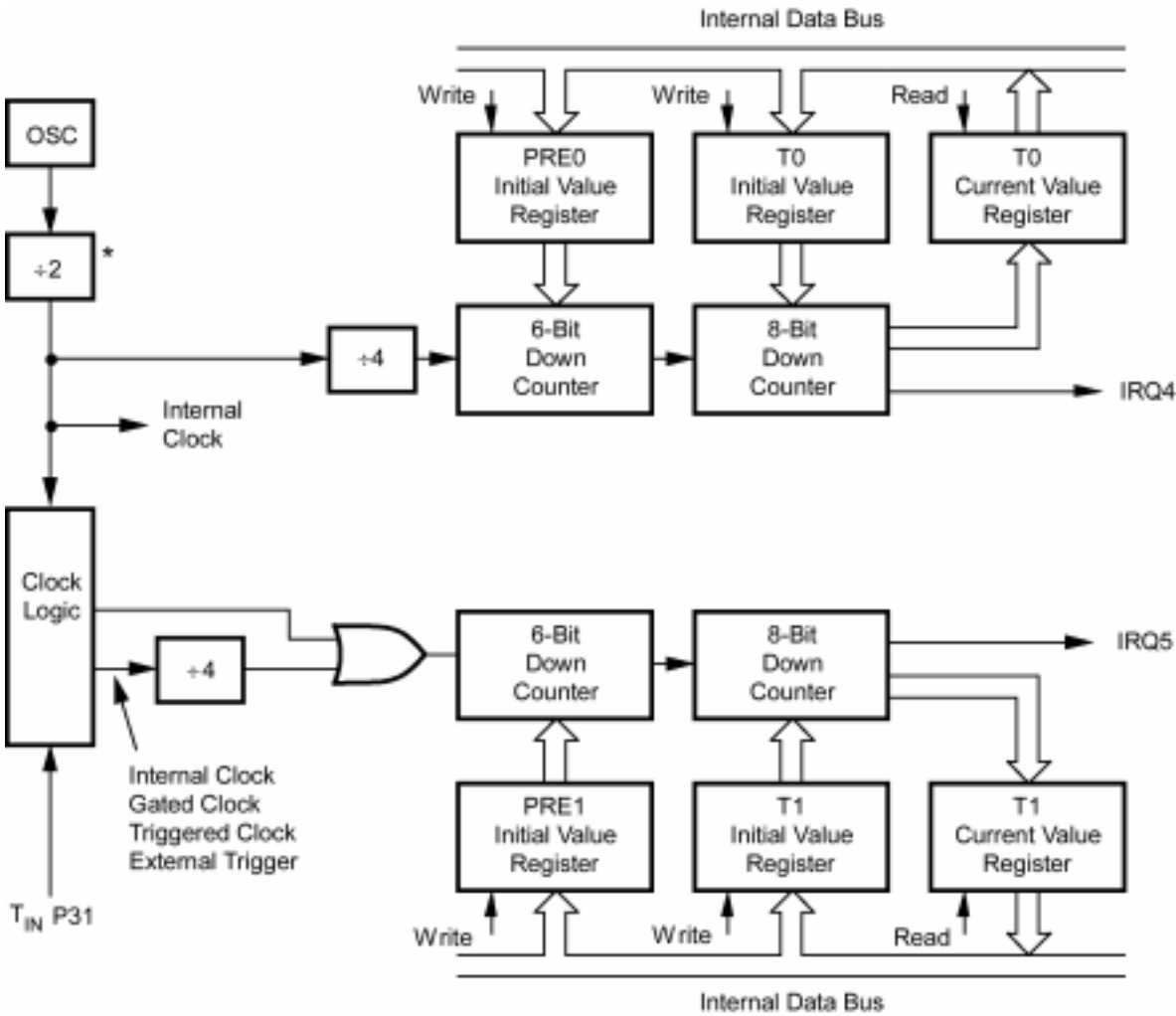
Figure 13. Counter/Timers Block Diagram

FUNCTIONAL DESCRIPTION (Continued)

Interrupts. The Z8 has six interrupts from six different sources. These interrupts are maskable and prioritized (Figure 14). The six sources are divided as follows: the falling edge of P31 (AN1), P32 (AN2), P33 (REF), the rising edge of P32 (AN2), and the two counter/timers. The Interrupt Mask Register globally or individually enables or disables the six interrupt requests (Table 2).

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority register. All Z8 interrupts are vectored through locations in program memory. When an Interrupt machine cycle is activated, an interrupt request is granted. The interrupt request disables all subsequent interrupts, saving the Program Counter and Status Flags. This request, in turn, branches to the program memory vector location reserved for that interrupt. The above-mentioned memory location and the next byte contain the 16-bit starting address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the interrupt request register is polled to determine which of the interrupt requests needs service.

Note: User must select any Z86C08 mode in ZiLOG's C12 ICEBOX™ emulator. The rising edge interrupt is not supported on the Z86CCP00ZEM emulator, except through a hardware/software workaround. See the Z86CCP User's Manual for complete information on the emulator.

Table 3. Interrupt Types, Sources, and Vectors

Name	Source	Vector Location	Comments
IRQ0	AN2(P32)	0,1	External (F) Edge
IRQ1	REF(P33)	2,3	External (F) Edge
IRQ2	AN1(P31)	4,5	External (F) Edge
IRQ3	AN2(P32)	6,7	External (R) Edge
IRQ4	T0	8,9	Internal
IRQ5	T1	10,11	Internal

Notes:
F = Falling edge triggered
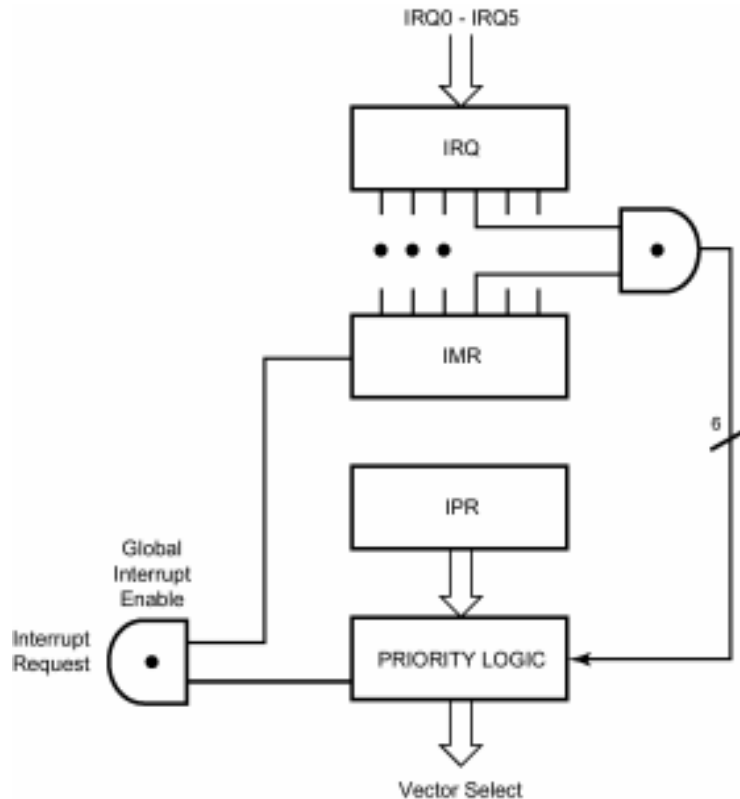R = Rising edge triggered

Figure 14. Interrupt Block Diagram

P R E L I M I N A R Y

Clock. The on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a RC, crystal, ceramic resonator, LC, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal should be AT cut, 4 MHz max, with a series resistance (RS) less than or equal to 100 ohms.

The crystal should be connected across XTAL1 and XTAL2 using the vendor's crystal recommended capacitors from each pin directly to device Ground pin 14 (Figure 14).

Note: Choosing the appropriate capacitor depends on the crystal manufacturer, ceramic resonator and PCB layout. The crystal capacitor loads should be connected to V_{SS} pin 14 to reduce ground noise injection.

To use a 32 kHz crystal, the 32 kHz operational mask option must be selected, and an external resistor R must be connected across XTAL1 and XTAL2. To use an RC oscillator, the RC oscillator option must be selected.

HALT Mode. This instruction turns off the internal CPU clock (not the crystal oscillation). The counter/timers and external interrupts IRQ0, IRQ1, IRQ2, and IRQ3 remain active. The device can be recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT.

STOP Mode. This instruction turns off the internal clock and external crystal oscillation, thereby reducing the standby current. The STOP Mode can be released by two methods. The first method is a RESET of the device by removing V_{CC} or dropping the V_{CC} below V_{LV}. The second method is if P27 is at a low level when the device executes the STOP

instruction. A Low condition on P27 releases the STOP Mode regardless if configured for input or output.

Program execution under both conditions begins at location 000C (Hex). However, when P27 is used to release the STOP Mode, the I/O port mode registers are not reconfigured to their default power-on conditions. This condition prevents any I/O, configured as output when the STOP instruction was executed, from glitching to an unknown state. To use the P27 release approach with STOP Mode, use the following instruction:

```
LD              P2M, #1XXX XXXXB
NOP
STOP
```
Note: (X = dependent upon user's application.)

In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To execute this instruction, the user must perform a NOP (opcode = FFH) immediately before the appropriate sleep instruction. The NOP is executed as follows:

```
FF      NOP        ; clear the pipeline
6F      STOP       ; enter STOP Mode
or
FF      NOP        ; clear the pipeline
7F      HALT       ; enter HALT Mode
```

Watch-Dog Timer (WDT). The Watch-Dog Timer is enabled by instruction WDT. When the WDT is enabled, it cannot be stopped by the instruction. With the WDT instruction, the WDT should be refreshed once the WDT is enabled within every Twdt period; otherwise, the Z8 resets itself. The WDT instruction affects the Flags accordingly: Z=1, S=0, V=0.
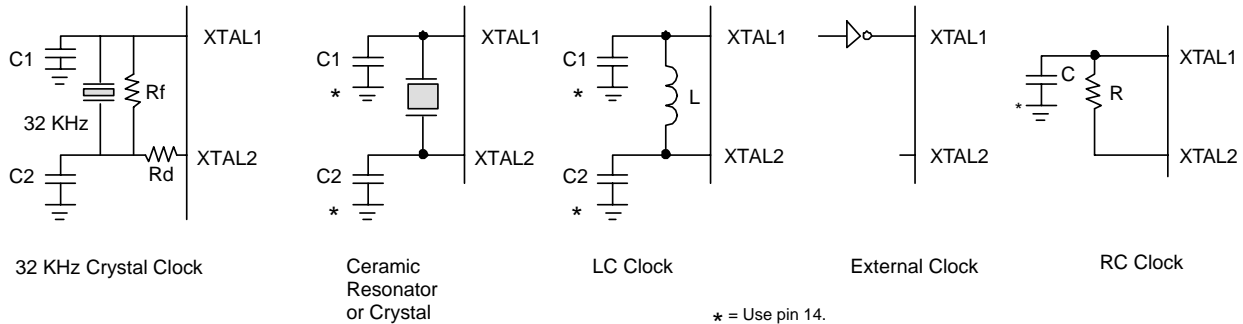
WDT = 5F (Hex)

Figure 15. Oscillator Configuration

FUNCTIONAL DESCRIPTION (Continued)

Opcode WDT (5FH). The first time Opcode 5FH is executed, the WDT is enabled, and subsequent execution clears the WDT counter. This action has to be performed within the maximum T_{WDT} period; otherwise, the WDT times out and generates a Reset. The generated Reset is the same as a Power-On Reset of T_{POR} plus 18 XTAL clock cycles. The WDT does not work (run) in STOP Mode. The WDT is disabled during and after a Reset, until the WDT is enabled again.

Opcode WDH (4FH). When this instruction is executed it will enable the WDT during HALT. If not, the WDT will stop when entering HALT. This instruction does not clear the counters; however, it does facilitate running the WDT function during HALT Mode. A WDH instruction executed without executing WDT (5FH) has no effect.

Permanent WDT Mask Option. Only when the Permanent WDT Mask Option is selected is the WDT hardwired to be enabled after reset. The WDT will operate in Run Mode, HALT Mode, and STOP Mode. The Opcode 5FH is used to refresh or clear the WDT counter. The WDT instruction (4FH) has no effect.

Note: The internal clock frequency is one-half the external clock frequency in SCLK = XTAL/2 mode.

Low-Voltage Protection (V_{LV}). Maximum (V_{LV}) Conditions: $T_A = –40°C, +105°C$; Internal Clock Frequency equal or less than 4 MHz.

The device will function normally at or above 3.0V under all conditions. Below 3.0V, the device functions normally until the Low-Voltage Protection trip point (V_{LV}) is reached. The device is guaranteed to function normally at supply voltages above the low voltage trip point for the temperatures and operating frequencies in Cases 1 and 2. The actual low voltage trip point is a function of temperature and process parameters (Figure 16).

1 MHz (Typical)

Temp	–40C°	0°C	+25°C	+70°C	+105°C	+125°C
V_{LV}	3.0	2.75	2.6	2.3	2.1	1.9

Note: See Figure 17 through Figure 34 for additional temperature and frequency-based measurements.

ROM Protect. ROM Protect fully shields any Z86108 ROM code from being read internally. *When ROM Protect is selected, ROM look-up tables can be used in this mode.*
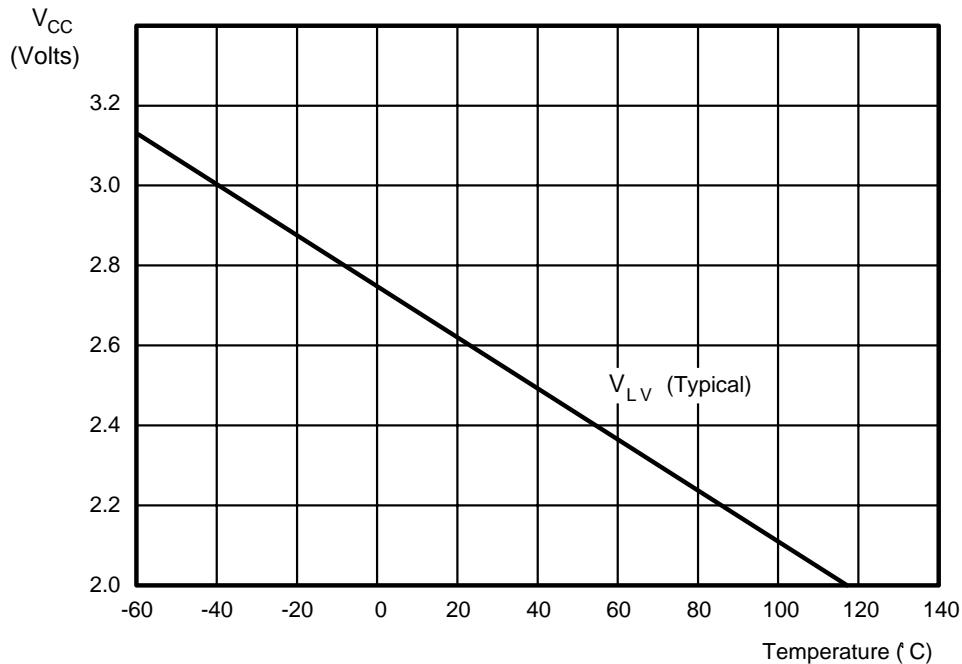

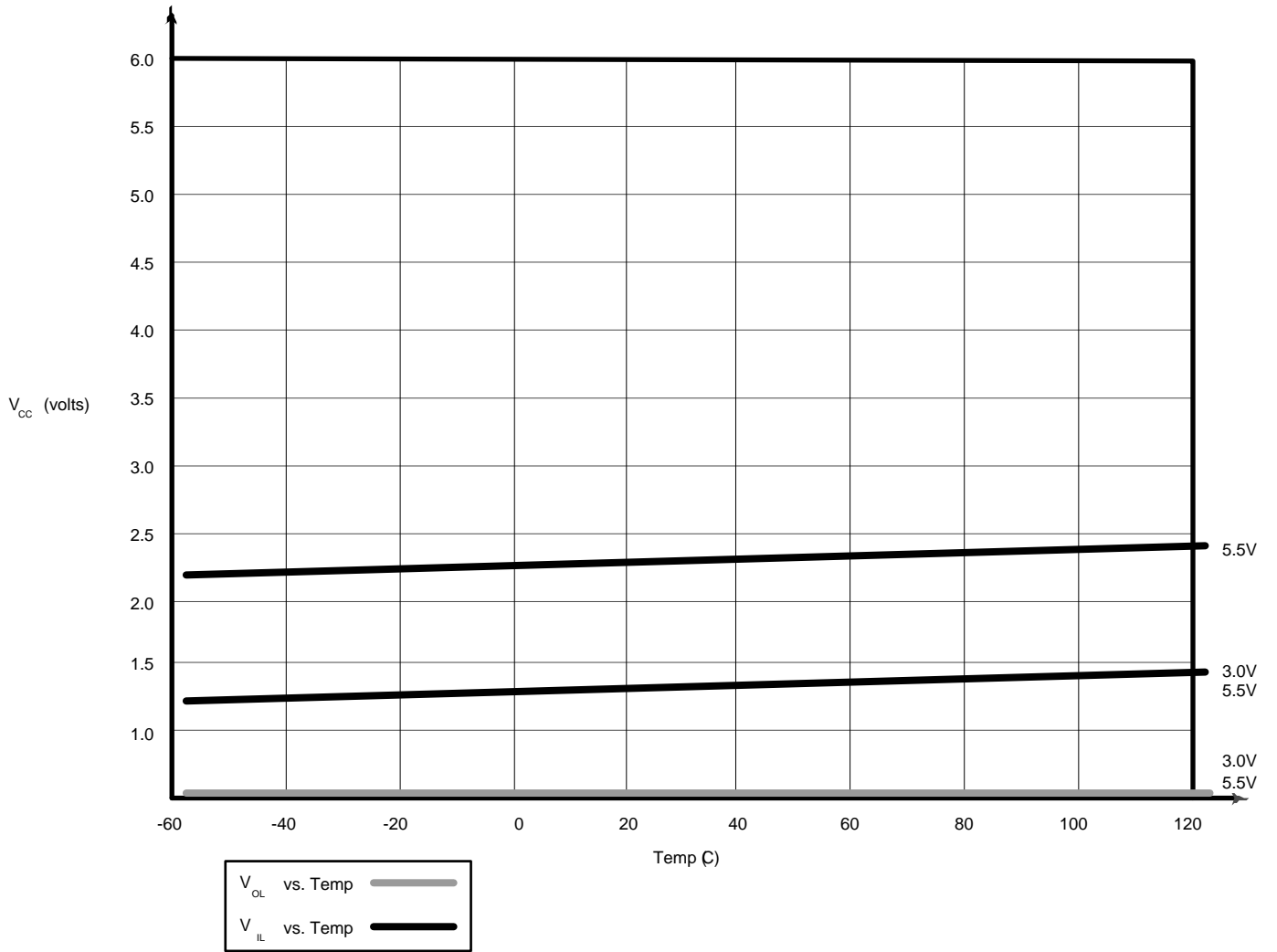
Figure 16. Typical Z86108 V_{LV} vs. Temperature

Figure 17. V_{IL}, V_{OL} vs. Temperature
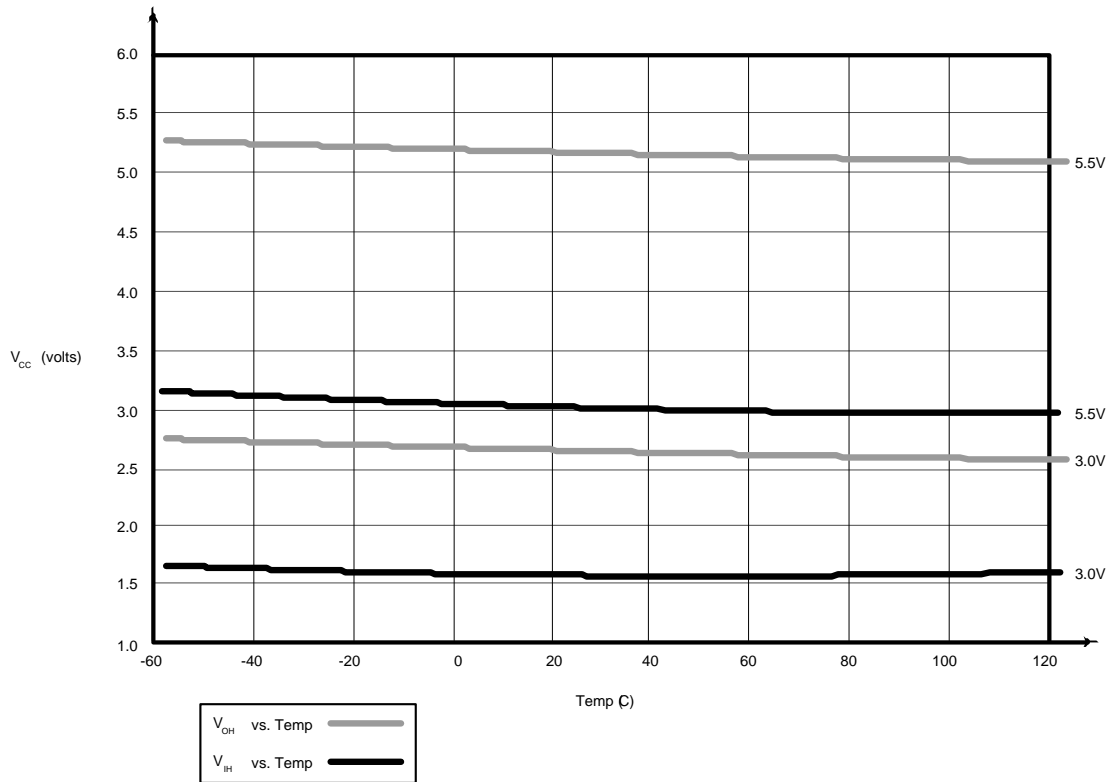
FUNCTIONAL DESCRIPTION (Continued)

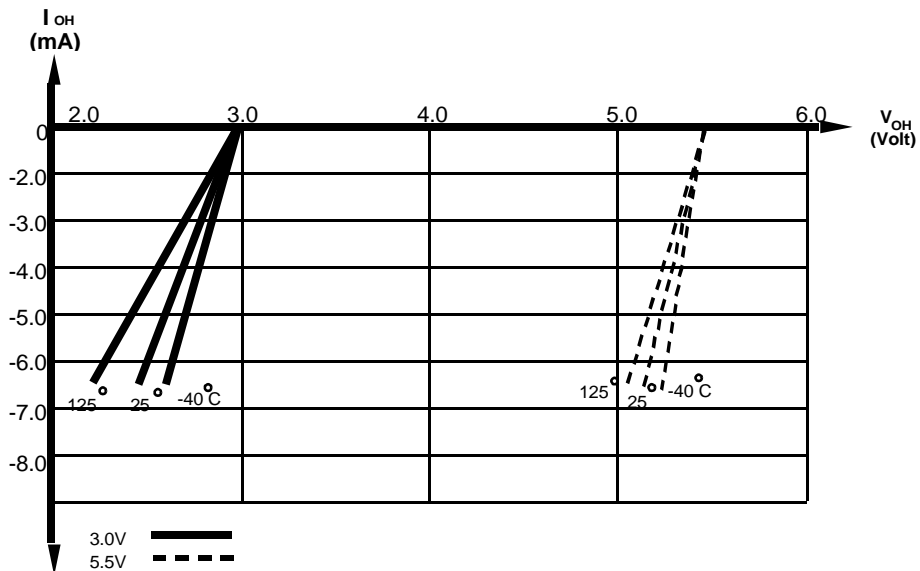**Figure 18. V_{IH}, V_{OH} vs. Temperature**

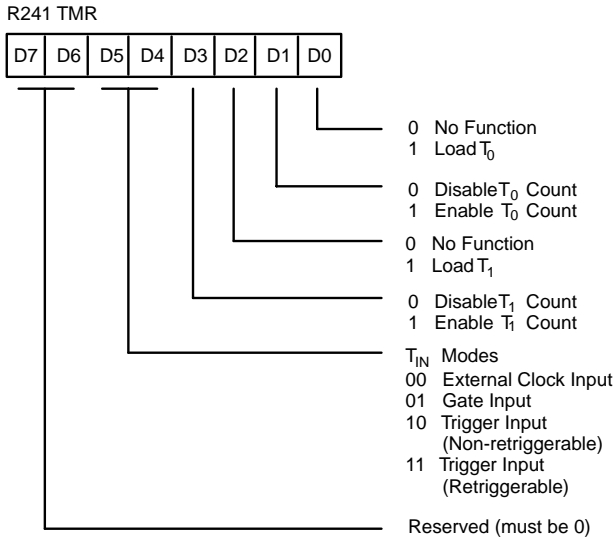**Figure 19. Typical I_{OH} vs. V_{OH}**

Z8 CONTROL REGISTER DIAGRAMS

R241 TMR

D7	D6	D5	D4	D3	D2	D1	D0

0 No Function
1 Load T_0

0 Disable T_0 Count
1 Enable T_0 Count

0 No Function
1 Load T_1

0 Disable T_1 Count
1 Enable T_1 Count

T_{IN} Modes
00 External Clock Input
01 Gate Input
10 Trigger Input
    (Non-retriggerable)
11 Trigger Input
    (Retriggerable)

Reserved (must be 0)

Figure 20. Timer Mode Register (F1$_H$: Read/Write)

R242 T1

D7	D6	D5	D4	D3	D2	D1	D0

T_1 Initial Value
(when WRITE;
range: 1-256 decimal,
01-00 hex)
T_1 Current Value
(when READ)
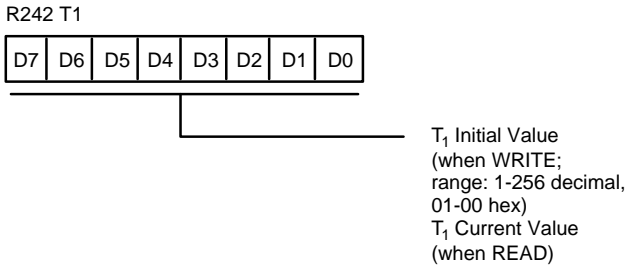
Figure 21. Counter Time 1 Register (F2$_H$: Read/Write)

R243 PRE1

D7	D6	D5	D4	D3	D2	D1	D0

Count Module
0 T_1 Single Pass
1 T_1 Modulo

Clock Source
1 T_1 Internal
0 T_1 External Timing
    Input (T_{IN}) Mode

Prescaler Modulo
(range: 1-64 decimal;
01-00 hex)
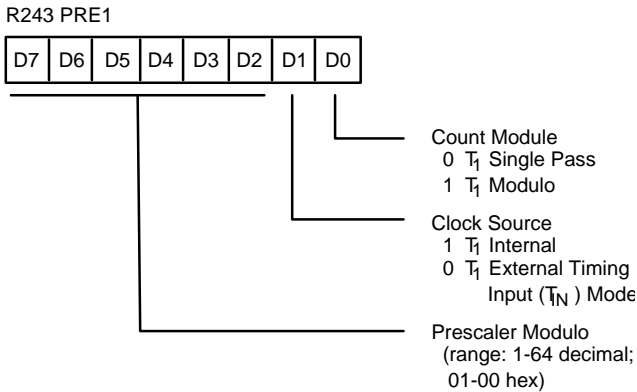
Figure 22. Prescaler 1 Register (F3$_H$: Write Only)

R244 T0

D7	D6	D5	D4	D3	D2	D1	D0

T_0 Initial Value
(when WRITE;
range: 1-256 decimal,
01-00 hex)
T_0 Current Value
(when READ)
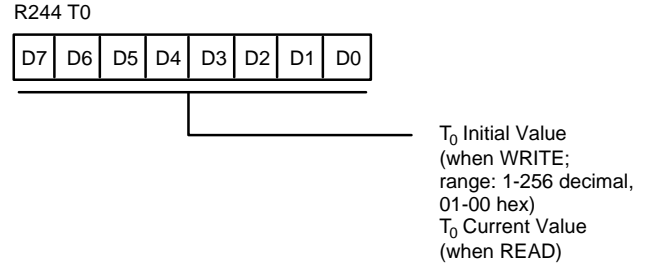
Figure 23. Counter/Timer 0 Register (F4$_H$: Read/Write)

R245 PRE0

D7	D6	D5	D4	D3	D2	D1	D0

Count Module
0 T_0 Single Pass
1 T_0 Modulo

Reserved (must be 0)

Prescaler Modulo
(range: 1-64 decimal;
01-00 hex)
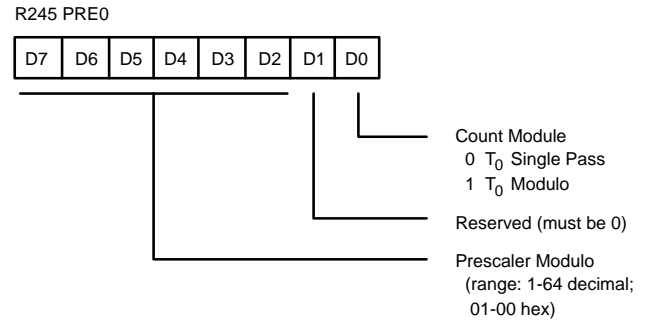
Figure 24. Prescaler 0 Register (F5$_H$: Write Only)

R246 P2M

D7	D6	D5	D4	D3	D2	D1	D0

$P2_7$-$P2_0$ I/O Definition
0 Defines bit as OUTPUT
1 Defines bit as INPUT
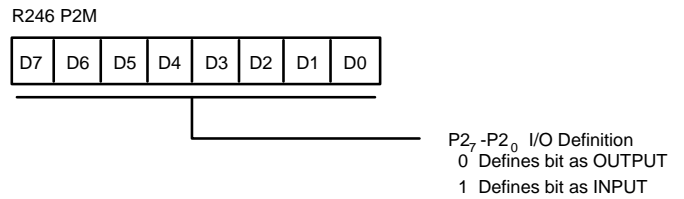
Figure 25. Port 2 Mode Register (F6$_H$: Write Only)

R247 P3M

D7	D6	D5	D4	D3	D2	D1	D0

0 Port 2 Open-Drain
1 Port 2 Push-Pull Active

Port 3 Inputs
0 Digital
1 Analog

Reserved (must be 0)
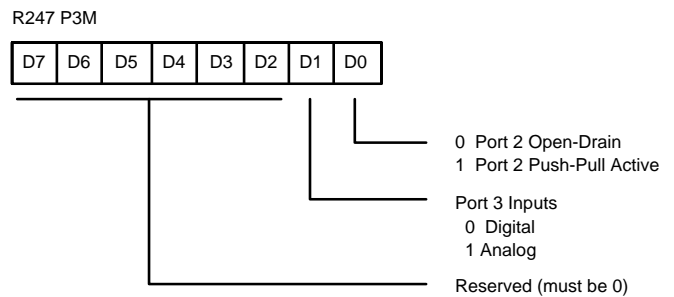
Figure 26. Port 3 Mode Register (F7$_H$: Write Only)

Z8 CONTROL REGISTER DIAGRAMS (Continued)

R248 P01M

D7	D6	D5	D4	D3	D2	D1	D0

PO_0-PO_3 Mode
00 = Output
01 = Input

Reserved (must be 1)

Reserved (must be 0)
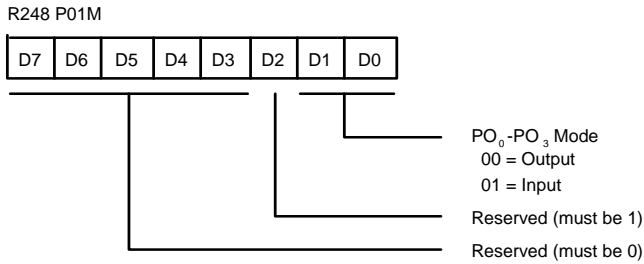
Figure 27. Port 0 and 1 Mode Register
($F8_H$: Write Only)

R249 IPR

D7	D6	D5	D4	D3	D2	D1	D0

Interrupt Group Priority
000   Reserved
001   C > A > B
010   A > B > C
011   A > C > B
100   B > C > A
101   C > B > A
110   B > A > C
111   Reserved

IRQ1, IRQ4 Priority (Group C)
0   IRQ1 > IRQ4
1   IRQ4 > IRQ1

IRQ0, IRQ2 Priority (Group B)
0   IRQ2 > IRQ0
1   IRQ0 > IRQ2

IRQ3, IRQ5 Priority (Group A)
0   IRQ5 > IRQ3
1   IRQ3 > IRQ5

Reserved (must be 0)

Figure 28. Interrupt Priority Register
($F9_H$: Write Only)

R250 IRQ

D7	D6	D5	D4	D3	D2	D1	D0

IRQ0 = P32 Input
IRQ1 = P33 Input
IRQ2 = P31 Input
IRQ3 = P32 Input
IRQ4 = T0
IRQ5 = T1

Reserved (must be 0)

Figure 29. Interrupt Request Register
(FA_H: Read/Write)

R51 IMR

D7	D6	D5	D4	D3	D2	D1	D0

1 Enables IRQ5-IRQ0
(D_0 = IRQ0)

Reserved (must be 0)

1 Enables Interrupts

Figure 30. Interrupt Mask Register (FB_H: Read/Write)

R252 Flags

D7	D6	D5	D4	D3	D2	D1	D0

User Flag F1

User Flag F2

Half Carry Flag

Decimal Adjust Flag

Overflow Flag

Sign Flag

Zero Flag

Carry Flag

Figure 31. Flag Register (FC_H: Read/Write)

R253 RP

D7	D6	D5	D4	D3	D2	D1	D0

Reserved (must be 0)

Register Pointer

Figure 32. Register Pointer (FD_H: Read/Write)

R255 SPL

D7	D6	D5	D4	D3	D2	D1	D0

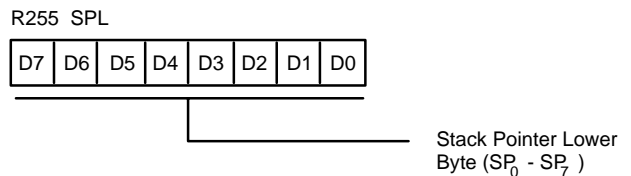Stack Pointer Lower
Byte (SP_0 - SP_7)

Figure 33. Stack Pointer (FF_H: Read/Write)

DEVICE CHARACTERISTICS
Standard Mode
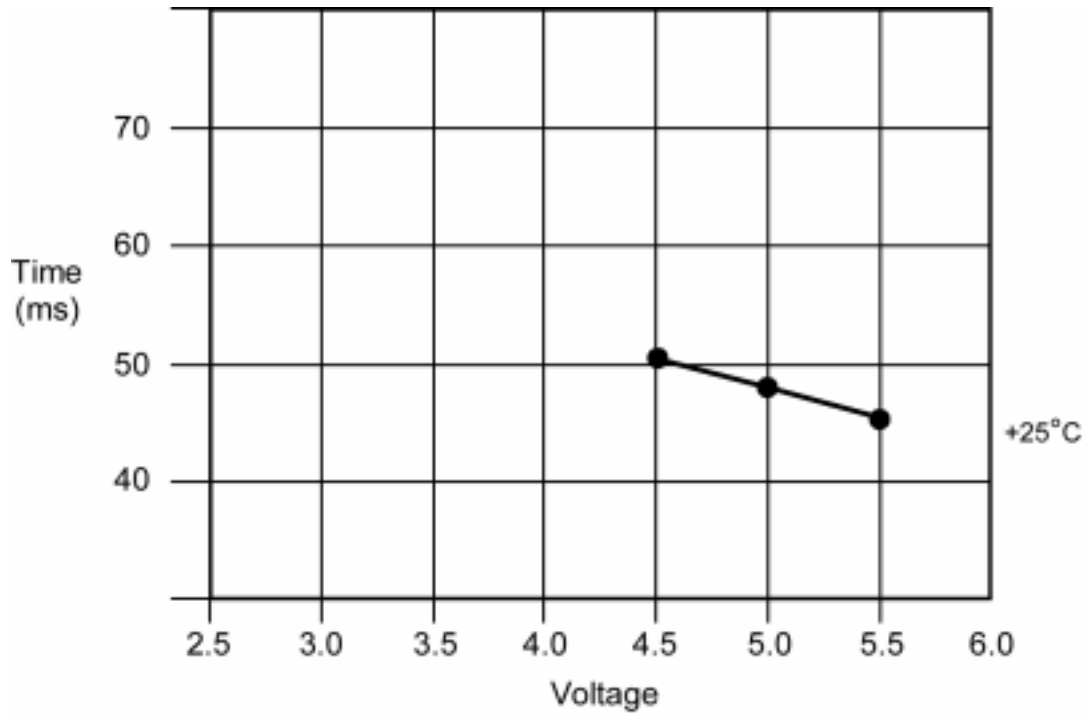
**Figure 34. Typical WDT Time Out Period vs. V$_{CC}$ Over Temperature**

PACKAGE INFORMATION
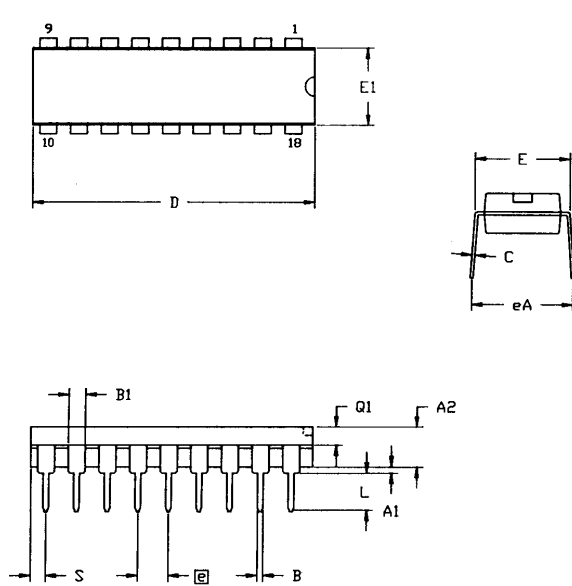
SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
e	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

Figure 35. 18-Pin DIP Package Diagram
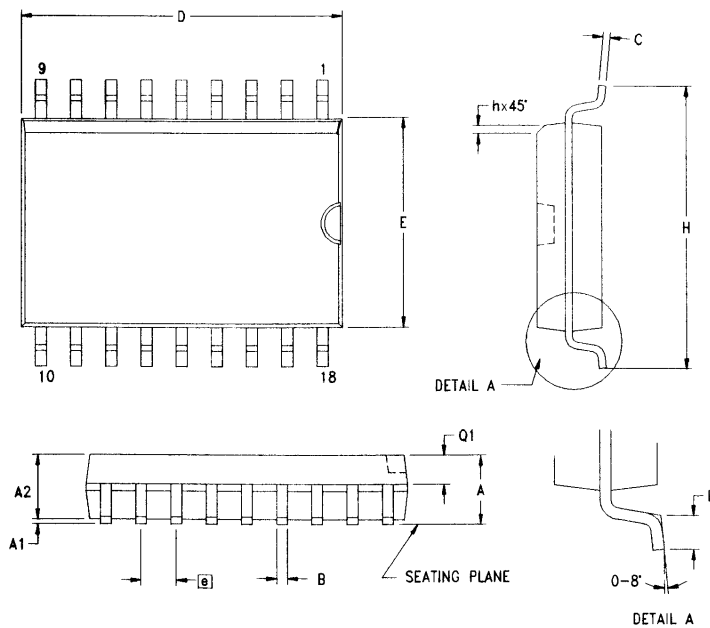
SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
e	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 36. 18-Pin SOIC Package Diagram

ORDERING INFORMATION

Z86108 (4 MHz)

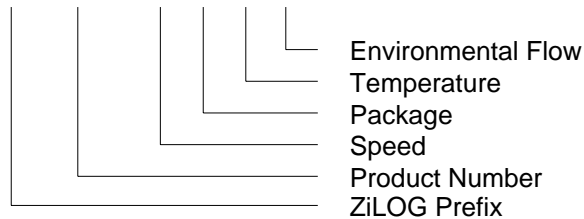| Standard Temperature	
18-Pin DIP	18-Pin SOIC
Z8610804PSC	Z8610804PSC
Extended Temperature	
18-Pin DIP	18-Pin SOIC
Z8610804PEC	Z8610804SEC

For fast results, contact your local ZiLOG sale offices for assistance in ordering the part(s) desired.

CODES

Preferred Package	P = DIP
	S = SOIC
Preferred Temperature	S = 0°C to +70°C
Extended Temperature	E = −40°C to +105°C
Speeds	4 = 4 MHz
Environmental	C = Plastic Standard

Example:
```
Z   86108   04  P  S  C      is a Z86108, 4 MHz, DIP, 0C to +70C, Plastic Standard Flow

                             Environmental Flow
                             Temperature
                             Package
                             Speed
                             Product Number
                             ZiLOG Prefix
```

Pre-Characterization Product:

The product represented by this CPS is newly introduced and ZiLOG has not completed the full characterization of the product. The CPS states what ZiLOG knows about this product at this time, but additional features or non-conformance with some aspects of the CPS may be found, either by ZiLOG or its customers in the course of further application and characterization work. In addition, ZiLOG cautions that delivery may be uncertain at times, due to start-up yield issues.